

BCT48752

Dual 4:1 CMOS Analog Signal Multiplexer

GENERAL DESCRIPTION

The BCT48752 is a CMOS analog IC configured as two 4-channel multiplexer. This CMOS device can operate from 2.5V to 5.5V single supplies. Each switch can handle rail-to-rail analog signals. The off-leakage current is less than 1uA at 25°C. All digital inputs can support 1.8V logic control I/O.






APPLICATIONS

Battery-Operated Equipment
Audio and Video Signal Routing
Low-Voltage Data-Acquisition Systems
Communications Circuits
Automotive

FEATURES

- Guaranteed On-Resistance
 - 48Ω (TYP) with +5V Supply
- Guaranteed On-Resistance Match Between Channels
 - 1.5Ω (TYP) with +5V Supply
- High -3dB Bandwidth: 300MHz
- Low Off-Leakage Current 1uA (MAX) at +25°C
- Low On-Leakage Current 1uA (MAX) at 25°C
- 2.5V to 5.5V Single-Supply Operation
- 1.8V Logic Compatible
- High Off-Isolation: -83dB(RL=50Ω, f=1MHz)
- -40°C to 85°C Operating Temperature Range
- Available in Green QFN-3x3-16L , SOP16 , SSOP16 or TSSOP16 Packages

ORDERING INFORMATION

Order Number	Package Type	Temperature Range	Marking	QTY/Reel
BCT48752EGE-TR	QFN3x3-16L	-40°C to +85°C	 48752 XXXXX	3000
BCT48752EOE-TU	SOP16	-40°C to +85°C	 48752 XXXXX	--
BCT48752EOE-TR	SOP16	-40°C to +85°C	 48752 XXXXX	3000
BCT48752ESE-TU	SSOP16	-40°C to +85°C	 48752 XXXXX	--
BCT48752ECE-TR	TSSOP16	-40°C to +85°C	 48752 XXXXX	3000

Note: "XXXXX" in Marking will be appeared as the batch code.



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ABSOLUTE MAXIMUM RATINGS

V _{CC} to GND	-0.3V to +6.0V
Voltage into Any Terminal	-0.3V to (V _{CC} + 0.3V)
Continuous Current into Any Terminal.....	±20mA
Peak Current, X ₋ , Y ₋ (Pulsed at 1ms, 10% duty cycle).....	±40mA
Storage Temperature Range.....	-65°C to +150°C
Junction Temperature.....	150°C
Operating Temperature Range.....	-40°C to +85°C
Lead Temperature (Soldering, 10 sec).....	260°C
ESD Susceptibility	
HBM.....	2000V
MM.....	200V

NOTE:

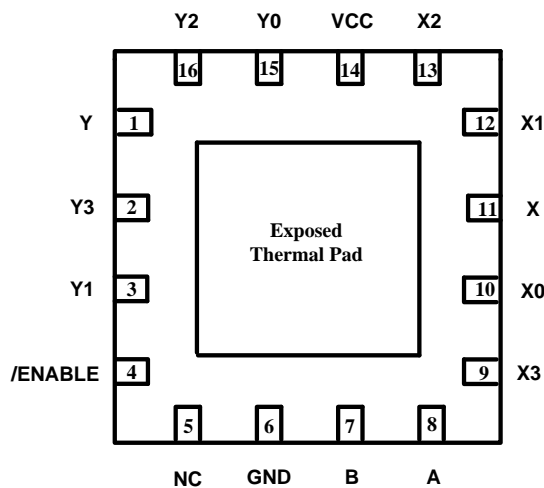
Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

CAUTION

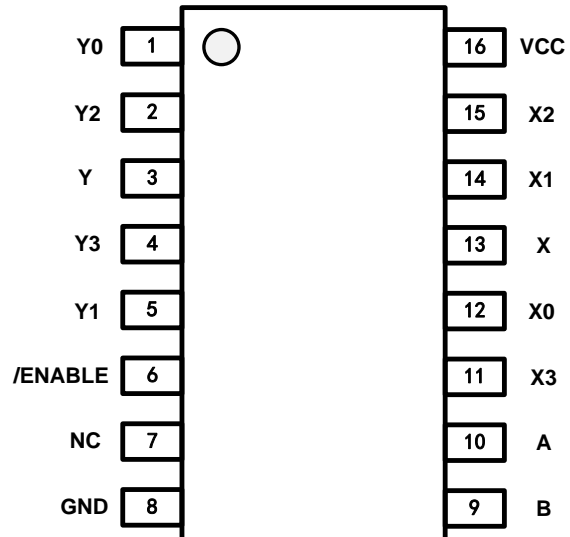
This integrated circuit can be damaged by ESD if you don't pay attention to ESD protection. Broadchip recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Broadchip reserves the right to make any change in circuit design, specification or other related things if necessary without notice at any time. Please contact Broadchip sales office to get the latest datasheet.

PIN CONFIGURATION (TOP VIEW)



QFN3x3-16L



SOP16/SSOP16/TSSOP16

PIN DESCRIPTION

PIN		NAME	FUNCTION
QFN3x3-16L	SOP16 SSOP16 TSSOP16		
15,3,16,2	1,5,2,4	Y0-Y3	Analog Switch Y Inputs Y0-Y3.
1	3	Y	Analog Switch "Y" Output.
4	6	/ENABLE	Digital Enable Input. Normally connected to GND.
5	7	NC	No Connect.
6	8	GND	Ground. Connect to digital ground.
7	9	B	Digital Address "B" Input.
8	10	A	Digital Address "A" Input.
10,12,13,9	12,14,15,11	X0-X3	Analog Switch X Inputs X0-X3.
11	13	X	Analog Switch "X" Output.
14	16	V _{CC}	Positive Analog and Digital Supply Voltage Input.
Exposed Pad	-	EP	Exposed Pad. Connect EP to GND.

FUNCTION TABLE

/ENABLE INPUT	SELECT INPUTS		ON SWITCHES
	B	A	
H	X	X	All Switches Open.
L	L	L	X-X0, Y-Y0
L	L	H	X-X1, Y-Y1
L	H	L	X-X2, Y-Y2
L	H	H	X-X3, Y-Y3

X=Don't care

NOTE: Input and output pins are identical and interchangeable. Either maybe considered an input or output; signals pass equally will in either direction.

ELECTRICAL CHARACTERISTICS

($V_{CC} = 5.0V$, typical values are at $T_A = +25^\circ C$, unless otherwise specified.)

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
ANALOG SWITCH						
Analog Signal Range	V_{X-}, V_{X+} V_{Y-}, V_{Y+}		GND		V_{CC}	mV
On-Resistance	R_{ON}	$I_X, I_Y = 1mA$		48	58	Ω
On-Resistance Match Between Channels	ΔR_{ON}	$I_X, I_Y = 1mA$		1.5	5	Ω
On-Resistance Flatness	$R_{FLAT(ON)}$	$I_X, I_Y = 1mA$		17	25	Ω
X_-, Y_- Off Leakage Current	$I_{X(OFF)}$ $I_{Y(OFF)}$	$V_{X-}, V_{Y-} = 4.5V$ or $1V$,			1	μA
X, Y Off Leakage Current	$I_{X(OFF)}$ $I_{Y(OFF)}$	$V_X, V_Y = 4.5V$ or $1V$			1	μA
X, Y On Leakage Current	$I_{X(ON)}$ $I_{Y(ON)}$	$V_X, V_Y = 4.5V$ or $1V$			1	μA
DIGITAL I/O						
Input Voltage High	V_{IH}	A, B, /ENABLE Pin	1.7			V
Input Voltage Low	V_{IL}	A, B, /ENABLE Pin			0.5	V
Input Current High	I_{IH}	$V_A, V_B, V_{/ENABLE} = V_{CC}$		1	1000	nA
Input Current Low	I_{IL}	$V_A, V_B, V_{/ENABLE} = 0V$		1	1000	nA
DYNAMIC CHARACTERISTICS						
Address Transition Time	t_{TRANS}	$V_{X-}, V_{Y-} = 3V$, $R_L = 300\Omega, C_L = 35pF$		85		ns
/ENABLE Turn-On Time	t_{ON}	$V_{X-}, V_{Y-} = 3V$, $R_L = 300\Omega, C_L = 35pF$		60		ns
/ENABLE Turn-Off Time	t_{OFF}	$V_{X-}, V_{Y-} = 3V$, $R_L = 300\Omega, C_L = 35pF$		70		ns
Internal A, B Rise Time	t_R	$V_{X-}, V_{Y-} = 3V$, $R_L = 300\Omega, C_L = 35pF$		45		ns
Internal A, B Fall Time	t_F	$V_{X-}, V_{Y-} = 3V$, $R_L = 300\Omega, C_L = 35pF$		50		ns
Break-Before-Make Time Delay	t_D	$V_{X-}, V_{Y-} = 3V$, $R_L = 300\Omega, C_L = 35pF$		50		ns
Charge Injection	Q	$R_S = 0\Omega, C_L = 1nF$		6		pC



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(Continued)

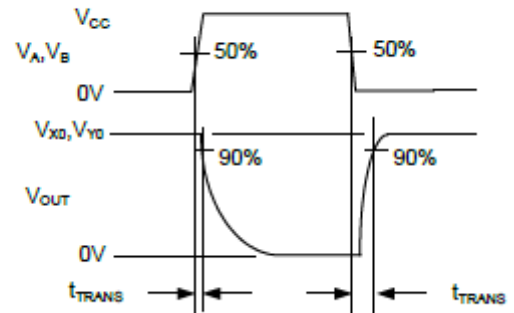
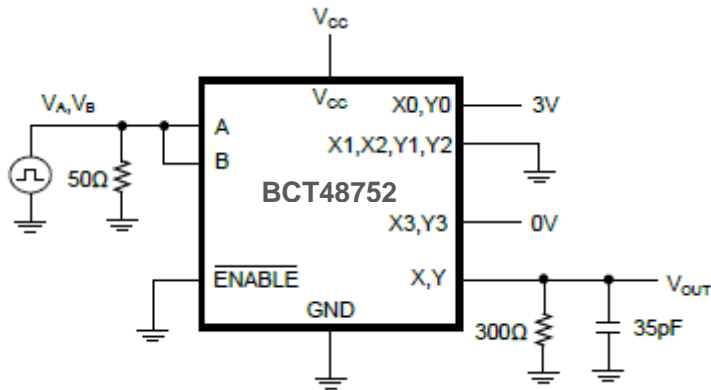
PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
ANALOG SWITCH						
Input Off-Capacitance	$C_{X(OFF)}$ $C_{Y(OFF)}$	$V_{X-}, V_{Y-}=0V, f=1MHz$		4.7		pF
Output Off-Capacitance	$C_{X(OFF)}$ $C_{Y(OFF)}$	$V_{X-}, V_{Y-}=0V, f=1MHz$		12.7		pF
Output On-Capacitance	$C_{X(ON)}$ $C_{Y(ON)}$	$V_{X-}, V_{Y-}=0V, f=1MHz$		16		pF
-3dB Bandwidth	BW	$R_L=50\Omega$		300		MHz
Off Isolation	O_{ISO}	$R_L=50\Omega, f=1MHz$		-83		dB
Total Harmonic Distortion	THD	$R_L=600\Omega, 5V_{P-P}, f=20Hz$ to 20kHz		0.7		%
Power Supply						
Power Supply Range	V_{CC}		2.5		5.5	V
Power Supply Current	I_{CC}	$V_{CC}=5V, V_A, V_B, V_{ENABLE}=V_{CC}$ or 0		0.001	6	uA

ELECTRICAL CHARACTERISTICS

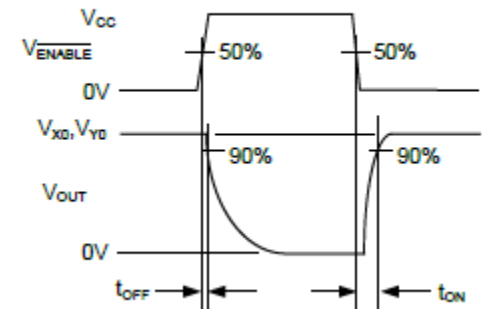
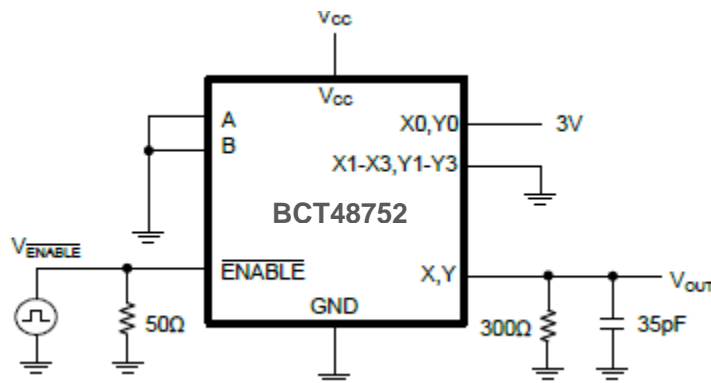
($V_{CC}=3.3V$, typical values are at $T_A=+25^{\circ}C$, unless otherwise specified.)

PARAMETER	SYM	CONDITIONS	MIN	TYP	MAX	UNITS
ANALOG SWITCH						
Analog Signal Range	V_{X-}, V_{X+} V_{Y-}, V_{Y+}		GND		V_{CC}	mV
On-Resistance	R_{ON}	$I_X, I_Y=1mA$		80	110	Ω
X_{-}, Y_{-} Off Leakage Current	$I_{X(OFF)}$ $I_{Y(OFF)}$	$V_{X-}, V_{Y-}=1V, 3V$			1	μA
X, Y Off Leakage Current	$I_{X(OFF)}$ $I_{Y(OFF)}$	$V_X, V_Y=1V, 3V$			1	μA
X, Y On Leakage Current	$I_{X(ON)}$ $I_{Y(ON)}$	$V_X, V_Y=1V, 3V$			1	μA
DIGITAL I/O						
Input Voltage High	V_{IH}	A, B, /ENABLE Pin	1.7			V
Input Voltage Low	V_{IL}	A, B, /ENABLE Pin			0.5	V
Input Current High	I_{IH}	$V_A, V_B, V_{/ENABLE}=V_{CC}$		1	1000	nA
Input Current Low	I_{IL}	$V_A, V_B, V_{/ENABLE}=0V$		1	1000	nA
DYNAMIC CHARACTERISTICS						
Address Transition Time	t_{TRANS}	$V_{X-}, V_{Y-}=3V$, $R_L=300\Omega, C_L=35pF$		150		ns
/ENABLE Turn-On Time	t_{ON}	$V_{X-}, V_{Y-}=3V$, $R_L=300\Omega, C_L=35pF$		110		ns
/ENABLE Turn-Off Time	t_{OFF}	$V_{X-}, V_{Y-}=3V$, $R_L=300\Omega, C_L=35pF$		100		ns
Internal A, B Rise Time	t_R	$V_{X-}, V_{Y-}=3V$, $R_L=300\Omega, C_L=35pF$		80		ns
Internal A, B Fall Time	t_F	$V_{X-}, V_{Y-}=3V$, $R_L=300\Omega, C_L=35pF$		85		ns
Break-Before-Make Time Delay	t_D	$V_{X-}, V_{Y-}=3V$, $R_L=300\Omega, C_L=35pF$		80		ns
ANALOG SWITCH						
-3dB Bandwidth	BW	$R_L=50\Omega$		300		MHz
Charge Injection	Q	$R_S=0\Omega, C_L=1nF$		6		pC
POWER SUPPLY						
Power Supply Current	I_{CC}	$V_{CC}=3.3V, V_A, V_B$, $V_{/ENABLE}=V_{CC}$ or 0		0.001	3	μA

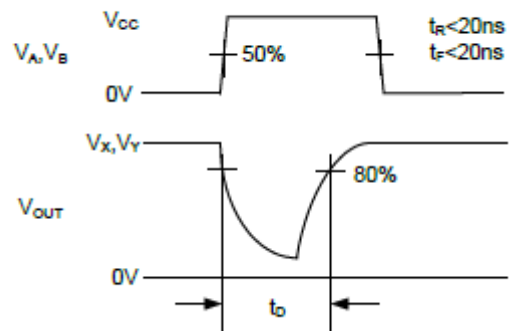
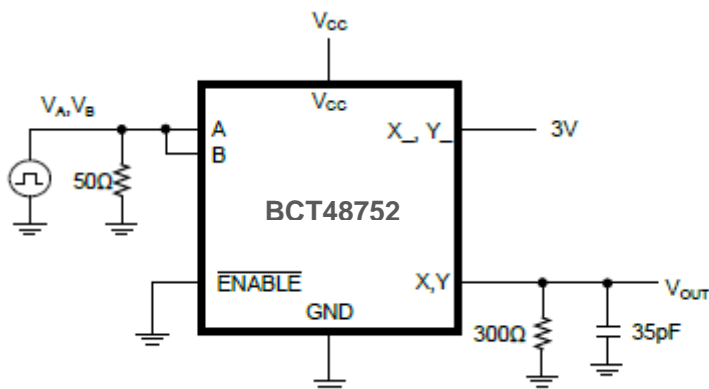
TEST CIRCUITS



Test Circuit 1. Address Transition Times (t_{TRANS})

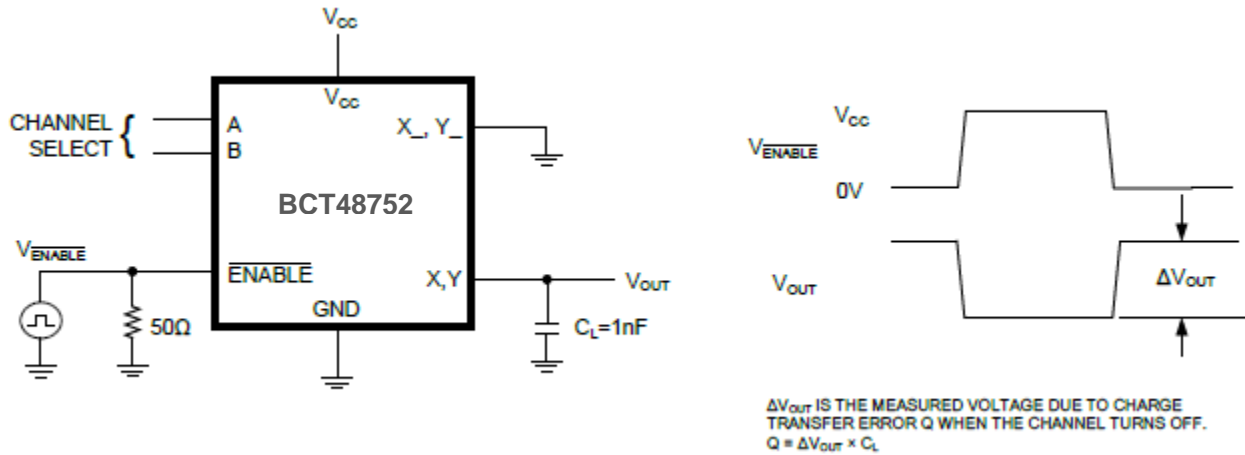


Test Circuit 2. Switching Times (t_{ON}, t_{OFF})

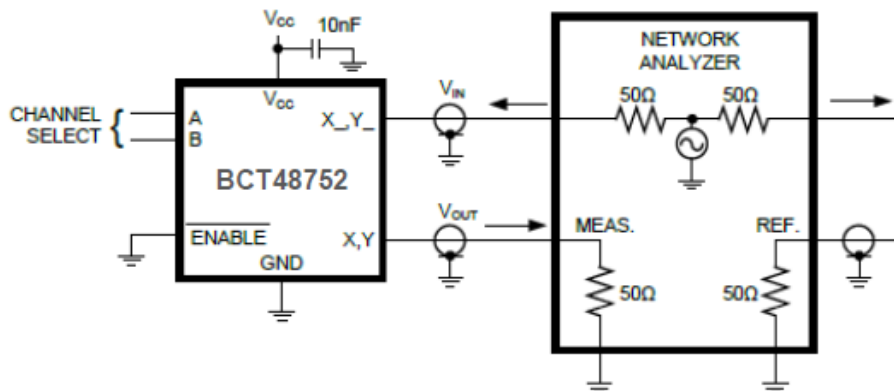


Test Circuit 3. Break-Before-Make Time Delay (t_D)

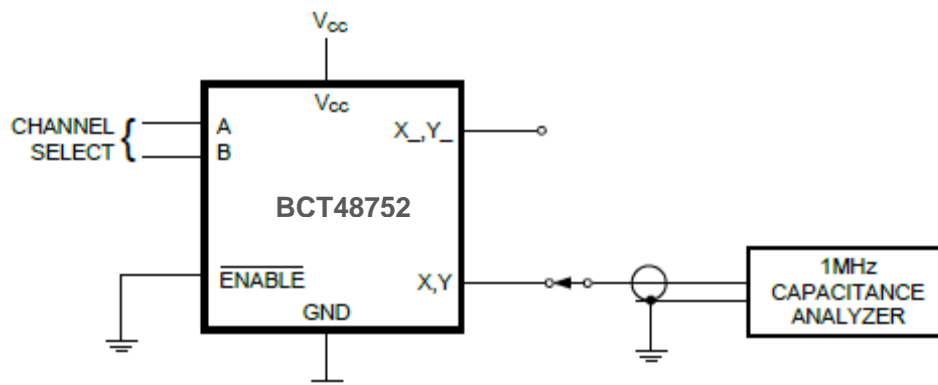
TEST CIRCUITS



Test Circuit 4. Charge Injection (Q)



Test Circuit 5. Off Isolation



Test Circuit 6. Capacitance

APPLICATION NOTES

Power-Supply Considerations

Overview

The BCT48752 construction is typical of most CMOS analog switch. It supports single power supply. V_{CC} and GND used to drive the internal CMOS switches and set the limits of the analog voltage on any switch. Reserve ESD protection diodes are internally connected between each analog-signal pin and both V_{CC} and GND. If any analog signal exceeds V_{CC} or GND, one of these diodes will conduct. During normal operation, these and other reverse-biased ESD diodes leak, forming the only current drawn from V_{CC} or GND.

Virtually all the analog leakage current comes from the ESD diodes. Although the ESD diodes on a given signal pin are identical and therefore fairly well balanced, they are reverse biased differently. Each is biased by either V_{CC} or GND and the analog signal. This means their leakages will vary as the signal varies. The difference in the two diode leakages to the V_{CC} and GND pins constitutes the analog-signal-path leakage current. All analog leakage current flows between each pin one of the supply terminals, not to the other switch terminal. This is why both sides of a given switch can show leakage currents of either the same or opposite polarity.

Over-Voltage Protection

Proper power-supply sequencing is recommended for the CMOS device. Do not

exceed the absolute maximum ratings because stresses beyond the listed ratings can cause permanent damage to the devices. Always sequence V_{CC} on first, followed by the logic inputs and analog signals. If power-supply sequencing is not possible, add one 100 resistor in series with the supply V_{CC} pin for over-voltage protection (Figure 1).

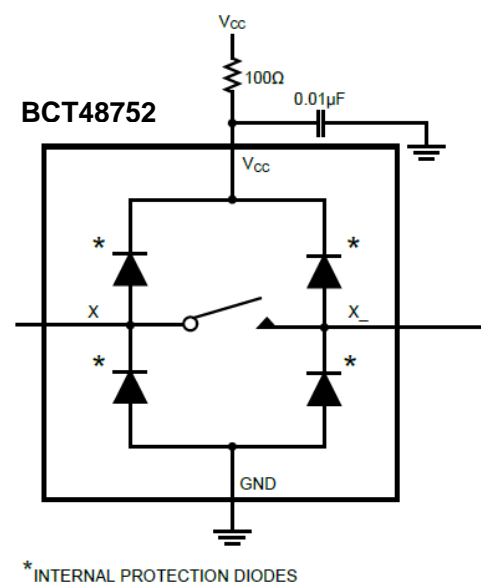
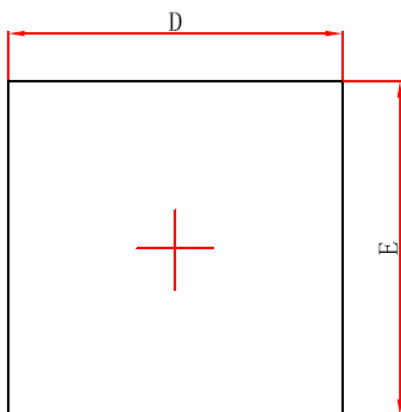


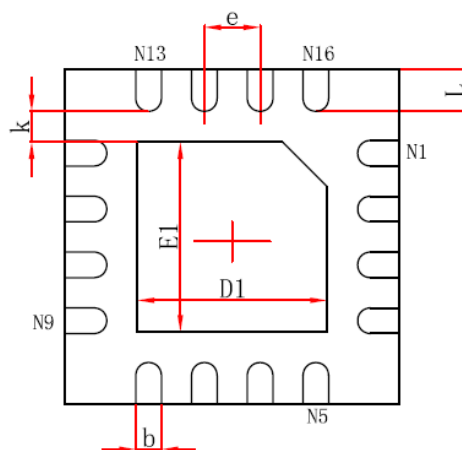
Figure 1. Over-Voltage Protection Using External Resistor

PACKAGE OUTLINE DIMENSIONS

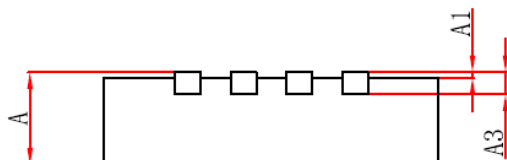
QFN3x3-16L



Top View



Bottom View



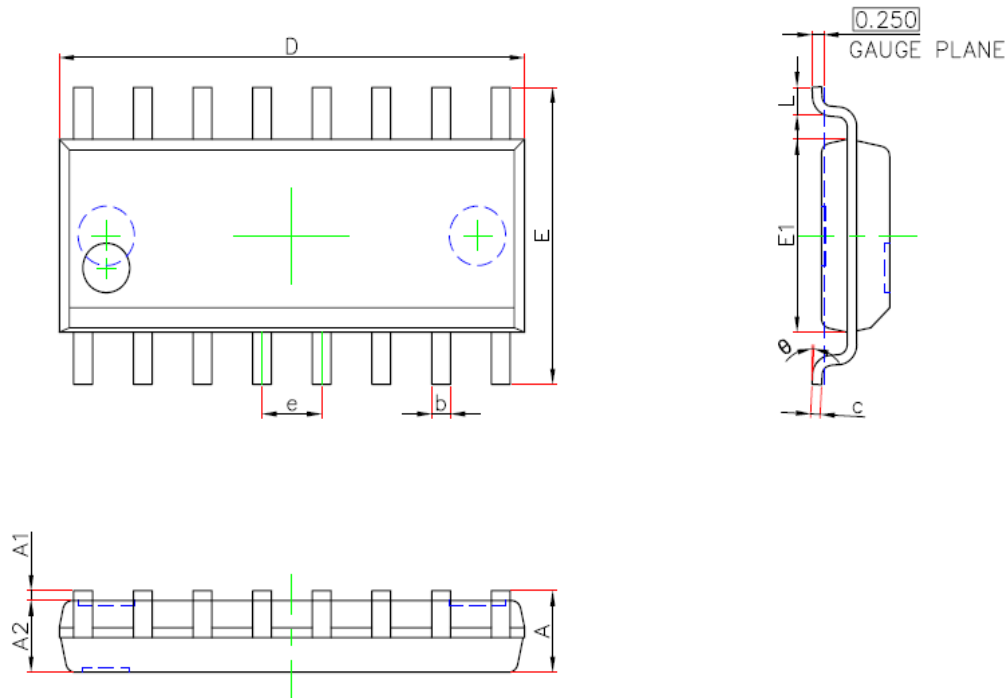
Side View

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF		0.008REF	
D	2.924	3.076	0.115	0.121
E	2.924	3.076	0.115	0.121
D1	1.600	1.800	0.063	0.071
E1	1.600	1.800	0.063	0.071
k	0.200MIN.		0.008MIN.	
b	0.180	0.280	0.007	0.011
e	0.500TYP.		0.020TYP.	
L	0.324	0.476	0.013	0.019

QFN3X3-16L Surface Mount Package

PACKAGE OUTLINE DIMENSIONS

SOP16

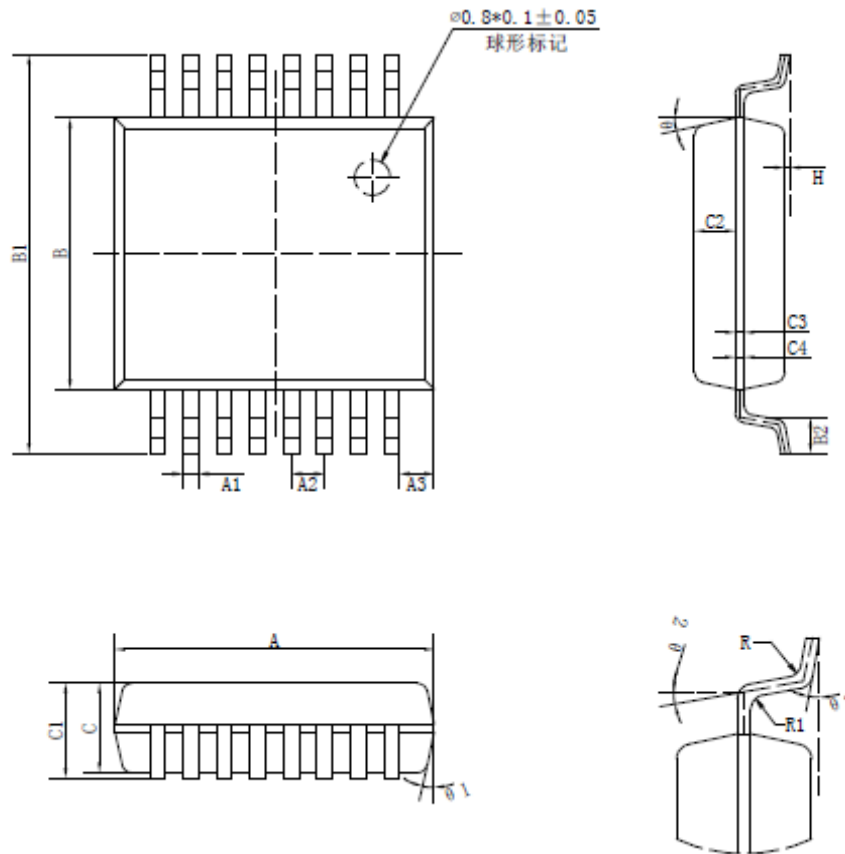


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A		1.750		0.069
A1	0.150	0.250	0.006	0.010
A2	1.400	1.500	0.055	0.059
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	9.800	10.000	0.386	0.394
e	1.270(BSC)		0.050(BSC)	
E	5.900	6.100	0.232	0.240
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

SOP16 Surface Mount Package

PACKAGE OUTLINE DIMENSIONS

SSOP16

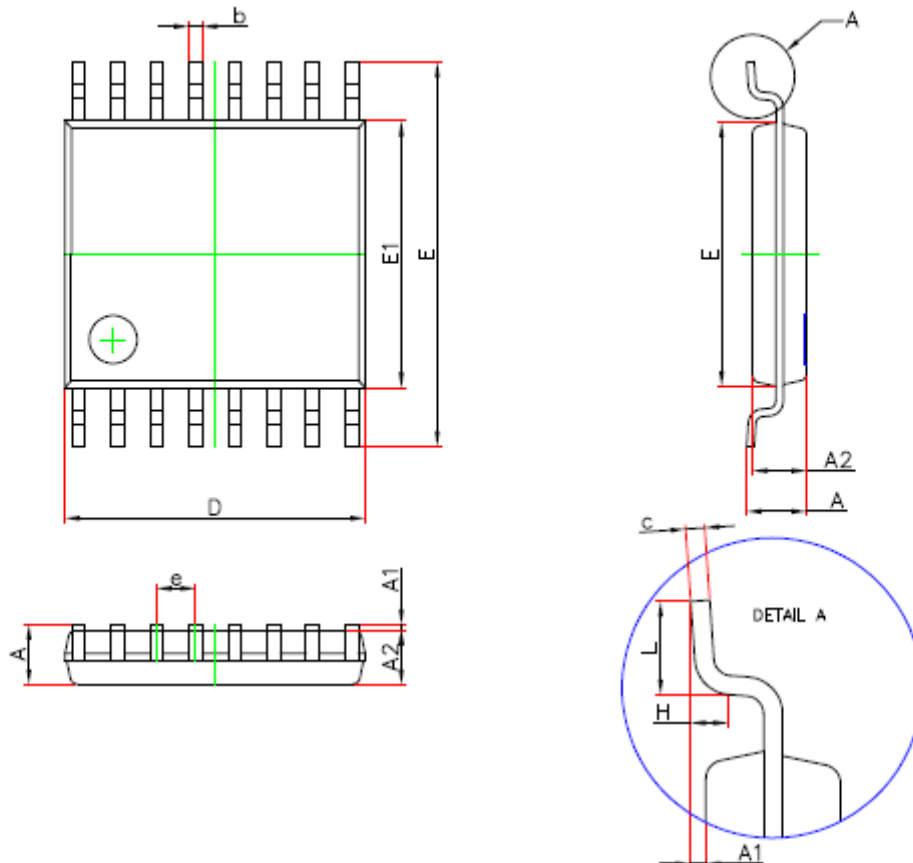


Symbol	Min	Max	Symbol	Min	Max
A	6.15	6.25	C3	0.152 TYP	
A1	0.30 TYP		C4	0.172 TYP	
A2	0.65 TYP		H	0.05	0.06
A3	0.675 TYP		θ	12° TYP	
B	5.25	5.35	$\theta 1$	12° TYP	
B1	7.65	7.95	$\theta 2$	10° TYP	
B2	0.60	0.80	$\theta 3$	0°	8°
C	1.70	1.80	R	0.20 TYP	
C1	1.75	1.95	R1	0.15 TYP	
C2	0.799 TYP				

SSOP16 Surface Mount Package (unit: mm)

PACKAGE OUTLINE DIMENSIONS

TSSOP16



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	—	1.200	—	0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.000	0.031	0.039
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D	4.900	5.100	0.193	0.201
E	6.250	6.550	0.246	0.258
E1	4.300	4.500	0.169	0.177
e	0.650(BSC)		0.026(BSC)	
L	0.500	0.700	0.020	0.028
H	0.250(TYP)		0.010(TYP)	
θ	1°	7°	1°	7°

TSSOP16 Surface Mount Package